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(54) Title: COMPOSITION FOR PREVENTING CREEPING OF A FLUX FOR SOLDERING		
(57) Abstract The present invention relates to a composition for preventing creeping of a flux for soldering, which is free from a problem from the viewpoint of the global environment or working environment. The present invention provides a composition for preventing creeping of a flux for soldering, consisting of a composition comprising a polymer containing polymer units of an unsaturated ester containing a polyfluoroalkyl group, a fluorine-type surfactant and an aqueous medium. Further, the present invention provides a method for soldering by means of the composition. Furthermore, the present invention provides an electronic part or printed board soldered by the method. Still further, the present invention provides an electric appliance employing such an electronic part or printed board.		